

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Tien-Jen Cheng, et al.	Dated: December 11, 2006
Serial Number: 10/604,578	Examiner: Nathan W. Ha
Filing date: July 31, 2003	Group Art Unit: 2814 CONF. No.: 1577
Title: Encapsulated Pin Structure for Improved Reliability of Wafer	IBM Corporation D/18G, B/321, Zip 482 2070 Route 52 Hopewell Junction, NY 12533-6531

AMENDMENT UNDER 37 C.F.R. § 1.116

Hon. Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

Sir:

In response to the Final Office Action dated **October 11, 2006**, Applicant respectfully request reconsideration and allowance of the above-identified application as follows:

Amendments to the Claims are reflected in the listing of Claims beginning on page 2 of this paper.

Remarks begin on page 6 of this paper.